

BRBAV99WAQ

Rev.A Jul.-2024

/ Descriptions

JF K\$*) *

Silicon Diode in a SOT-323 Plastic Package.

/ Features

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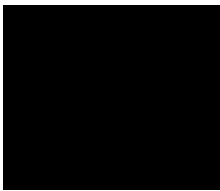
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Very small plastic SMD package, High switching speed, High Continuous reverse and Repetitive peak reverse voltage, High Repetitive peak forward current, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

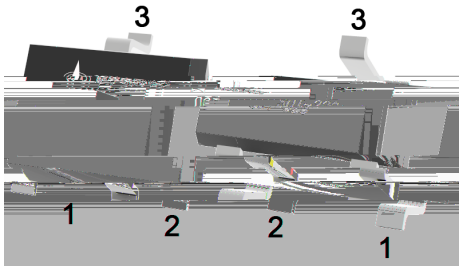
/ Applications

Applications for High-speed switching, surface mounted circuits, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit



/ Pinning



PIN: See Equivalent Circuit.

/ Marking

Marking	QA7
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@ f Parameter	... Z Symbol	f › Rating	% y Unit
Repetitive Reverse Voltage	V_{RRM}	85	V
Continuous reverse voltage	V_R	75	V
Continuous forward current	$I_{F(1)}$	150	mA
	$I_{F(2)}$	130	mA
Repetitive peak forward current	I_{FRM}	500	mA
Non-repetitive Peak Forward Current	$I_{FSM(1)(t=1\text{ S})}$	0.5	A
	$I_{FSM(2)(t=1\text{ mS})}$	1.0	A
	$I_{FSM(3)(t=1\text{ S})}$	4.0	A
Power Dissipation	P_D	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range			

F(1)

Ô ? d • Ž ¢ / Electrical Characteristic Curve

Ø □ =) ϕ / Package Dimensions

BRBAV99WAQ

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Note:

1o• Ä ½ “ † 150 ½200 - k ž • 60 ½120sec;

1.Preheating:150~200 - , Time:60~120sec.

2o• Q › “ † 255 r5 - k ž • 4 Ò 5 r0.5sec;

2.Peak Temp.:255 r5 - , Duration:5 r0.5sec.

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ~ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 -

ž • y 10 r1 sec.

Temp.:260±5

Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type
7>û ~ E

Units ;>û !H

Dimension ;>û p . (unit Åmm³